# **Gallium Nitride 28V 70W, RF Power Transistor**

#### **Description**

The NU6007H is a 70W ,GaN HEMT, designed for multiple applications with frequencies up to 3GHz.

There is no guarantee of performance when this part is used in applications designed Outside of these frequencies.

 $\bullet$  Typical performance (on Innogration narrow band fixture with device soldered)  $V_{DD}{=}28V~I_{DQ}{=}420mA,~CW.$ 

Frequency(MHz)	Gp (dB)	P <sub>1dB</sub> (W)	Efficiency (%)
1300	20	70	65

# NU6007H

#### **Applications and Features**

- Suitable for wireless communication infrastructure, wideband amplifier, EMC testing, ISM etc.
- High Efficiency and Linear Gain Operations
- Thermally Enhanced Industry Standard Package
- High Reliability Metallization Process
- Excellent thermal Stability and Excellent Ruggedness
- Compliant to Restriction of Hazardous Substances (RoHS)
  Directive 2002/95/EC

#### **Important Note: Proper Biasing Sequence for GaN HEMT Transistors**

#### **Turning the device ON**

- 1. Set VGS to the pinch--off (VP) voltage, typically -5 V
- 2. Turn on VDS to nominal supply voltage (28V)
- 3. Increase VGS until IDS current is attained
- 4. Apply RF input power to desired level

#### Turning the device OFF

- 1. Turn RF power off
- 2. Reduce VGS down to VP, typically -5 V
- 3. Reduce VDS down to 0 V
- 4. Turn off VGS

Table 1. Maximum Ratings (Not simultaneous, TC = 25°C unless otherwise noted)

Rating	Symbol	Value	Unit
DrainSource Voltage	$V_{ t DSS}$	160	Vdc
GateSource Voltage	$V_{\sf GS}$	-10,+2	Vdc
Operating Voltage	$V_{\scriptscriptstyle DD}$	40	Vdc
Maximum Forward Gate Current	Igmax	16	mA
Storage Temperature Range	Tstg	-65 to +150	°C
Case Operating Temperature	T <sub>c</sub>	+150	°C
Operating Junction Temperature(See note 1)	TJ	+200	°C
Total Device Power Dissipation (Derated above 25°C,see note 2)	Pdiss	100	W

- 1. Continuous operation at maximum junction temperature will affect MTTF
- 2. Bias Conditions should also satisfy the following expression: Pdiss < (Tj Tc) / RJC and Tc = Tcase

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#### **Table 2. Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction to Case	Rejc-dc	1.8	C/W
T <sub>C</sub> = 85°C, T <sub>J</sub> =200°C, DC Power Dissipation(See note 1)	Keac-DC	1.0	C/ VV

<sup>1.</sup> ReJC-DC is tested at only DC condition, it is related to the highest thermal resistance value among all test conditions. It might be differently lower in different RF operation conditions like CW signal ,pulsed RF signal etc.

Table 3. Electrical Characteristics (Tcase = 25°C unless otherwise noted)

#### **DC Characteristics**

Characteristic	Conditions	Symbol	Min	Тур	Max	Unit
Drain-Source Breakdown Voltage	V <sub>GS</sub> =-8V; I <sub>DS</sub> =16mA	$V_{DSS}$	150			V
Gate Threshold Voltage	V <sub>DS</sub> = 28V, I <sub>D</sub> = 16 mA	V <sub>GS</sub> (th)		-2.7		V
Gate Quiescent Voltage	V <sub>DS</sub> =28V, I <sub>DS</sub> =420mA, Measured in Functional Test	V <sub>GS(Q)</sub>		-2.4		V

#### Functional Tests (In Innogration narrow band Test Fixture, 50 ohm system) : $V_{DD}$ = 28 Vdc, $I_{DQ}$ = 420 mA, f = 1300 MHz, CW

Characteristic	Symbol	Min	Тур	Max	Unit
Power Gain	Gp		20		dB
Drain Efficiency @ P <sub>1dB</sub>	Eff		65		%
1dB compressed Power	P <sub>SAT</sub>		70		W
Input Return Loss	IRL		-7		dB
Mismatch stress at all phases (Device no damage)	VSWR		10:1		Ψ

# **NU6007H GaN TRANSISTOR**

# **Package Outline**

Flanged ceramic package; 2 leads

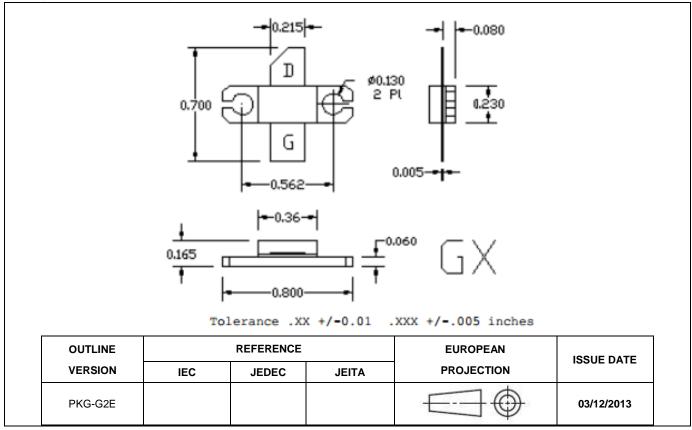


Figure 1. Package Outline PKG-G2E

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### **Revision history**

#### Table 4. Document revision history

Date	Revision	Datasheet Status
2017/3/10	V1.0	Objective Datasheet Creation
2017/6/19	V1.0	Preliminary Datasheet Creation

#### **Notice**

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